Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L30	2	US-6031723-$.DID.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 13:32
L31	7	US-6051093-$.DID. OR US-5808873-$.DID. OR US-6163456-$.DID. OR US-6531022-$.DID.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 13:34
L32	11	US-6184577-$.DID. OR US-5401688-$.DID. OR US-4751126-$.DID. OR US-6038133-$.DID. OR US-6338767-$.DID. OR US-5018051-$.DID.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 13:42
L33	2	US-6404052-$.DID.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 13:42
L34	11	("5434452" | "5488542" | "5789271" | "5821626" | "5877559" | "5995379" | "6124634" | "6157084" | "6211576" | "6242103").PN. OR ("6404052").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/11 14:07
L35	2	"6417060".pn.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 14:10
L36	82	electrodes adj making and 29/$.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 14:16
L37	0	electrodes adj matching near method and 29/$.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 14:17
L38	1	electrodes adj sandwich near separation	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 14:24
L39	947	electrodes adj sandwich	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 14:24
L40	16	electrodes adj sandwich and 29/$.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 14:31

L41	2	"6680441".pn.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 14:31
L42	9	("5161093" | "5336928" | "6180881" | "6239496" | "6292366" | "6359235" | "6404643" | "6469374" | "6512182").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/11 14:35
L43	50	pcb and embedded near component	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 14:36
L44	6	pcb and embedded near component and 29/$.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 14:37
L45	7	pcb and embedded near component and (29/832, 174/260 , 174/262 , 29/825 , 29/830 , 29/852 , 361/330 , 361/760).ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 15:05
L46	50	pcb and embedded near component	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 15:05
L47	0	pcb and resin near film and embedded near component	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 15:05
L48	19	resin near film and embedded near component	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 15:05
L49	11	("20020076919" | "20020119396" | "20030038373" | "20030075811" | "5353195" | "5872051" | "5874770" | "6038133" | "6570469" | "6576499" | "6784765").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/11 15:11
L50	6535	electrodes near making	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 15:12
L51	416	electrodes near making and "438"/$.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 15:12
L52	318	electrodes near making and "29"/$.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 15:29

L53	132	minh near trinh.xp.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 15:40
L54	2	"6038133".pn.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 15:40